

# FDMC8327L

## N-Channel PowerTrench® MOSFET 40 V, 14 A, 9.7 mΩ

### Features

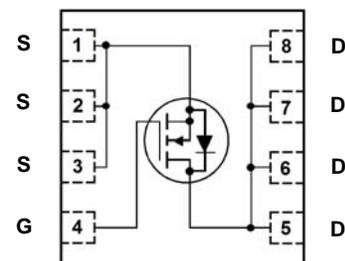
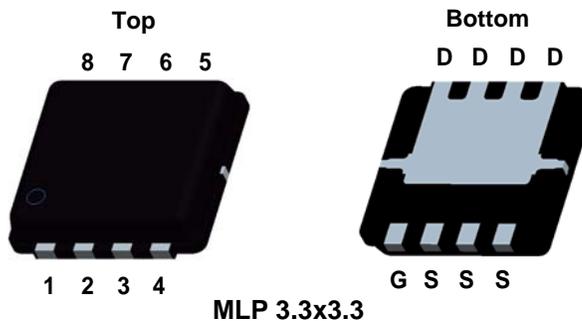
- Max  $r_{DS(on)}$  = 9.7 mΩ at  $V_{GS} = 10$  V,  $I_D = 12$  A
- Max  $r_{DS(on)}$  = 12.5 mΩ at  $V_{GS} = 4.5$  V,  $I_D = 10$  A
- Low Profile - 0.8mm max in Power 33
- 100% UIL test
- RoHS Compliant

### General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Application

- DC-DC Conversion



### MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rated	Units
$V_{DS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous (Package limited) $T_C = 25^\circ\text{C}$	14	A
	- Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	43	
	- Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	12	
	- Pulsed	60	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	25	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	30	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	2.3	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case (Note 1)	4.2	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC8327L	FDMC8327L	Power 33	13"	12 mm	3000 units

## Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		22		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$			$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\text{ }\mu\text{A}$	1.0	1.7	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , referenced to $25\text{ }^\circ\text{C}$		-5		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 12\text{ A}$		7.4	9.7	m $\Omega$
		$V_{GS} = 4.5\text{ V}$ , $I_D = 10\text{ A}$		9.4	12.5	
		$V_{GS} = 10\text{ V}$ , $I_D = 12\text{ A}$ , $T_J = 125\text{ }^\circ\text{C}$		11	14.5	
$g_{FS}$	Forward Transconductance	$V_{DD} = 5\text{ V}$ , $I_D = 12\text{ A}$		52		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 20\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$		1235	1850	pF
$C_{oss}$	Output Capacitance			347	520	pF
$C_{rss}$	Reverse Transfer Capacitance			21	35	pF
$R_g$	Gate Resistance		0.1	0.6	1.3	$\Omega$

### Switching Characteristics

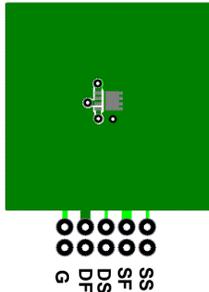
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 20\text{ V}$ , $I_D = 12\text{ A}$ , $V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\text{ }\Omega$		8.4	17	ns
$t_r$	Rise Time			2.2	10	ns
$t_{d(off)}$	Turn-Off Delay Time			20	32	ns
$t_f$	Fall Time			2.2	10	ns
$Q_{g(TOT)}$	Total Gate Charge		$V_{GS} = 0\text{ V to } 10\text{ V}$	$V_{DD} = 20\text{ V}$ , $I_D = 12\text{ A}$	18.5	26
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0\text{ V to } 5\text{ V}$	9.7		14	nC
$Q_{gs}$	Gate to Source Charge		3.3			nC
$Q_{gd}$	Gate to Drain "Miller" Charge		2.6			nC

### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 1.8\text{ A}$ (Note 2)		0.7	1.2	V
		$V_{GS} = 0\text{ V}$ , $I_S = 12\text{ A}$ (Note 2)		0.8	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 12\text{ A}$ , $di/dt = 100\text{ A/s}$		32	51	ns
$Q_{rr}$	Reverse Recovery Charge			10	20	nC

Notes:

1.  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a. 53  $^\circ\text{C/W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b. 125  $^\circ\text{C/W}$  when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty cycle < 2.0%.

3. Starting  $T_J = 25\text{ }^\circ\text{C}$ ; N-ch:  $L = 0.3\text{ mH}$ ,  $I_{AS} = 13\text{ A}$ ,  $V_{DD} = 36\text{ V}$ ,  $V_{GS} = 10\text{ V}$ .

**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted

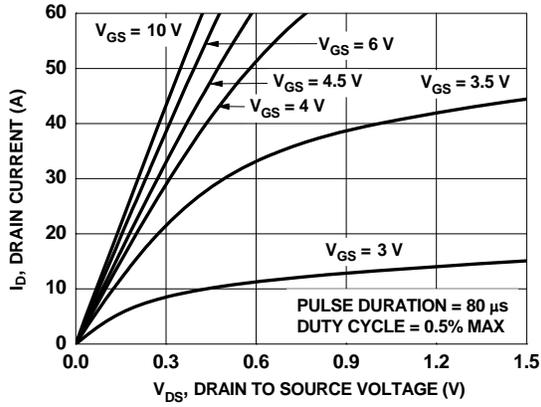


Figure 1. On Region Characteristics

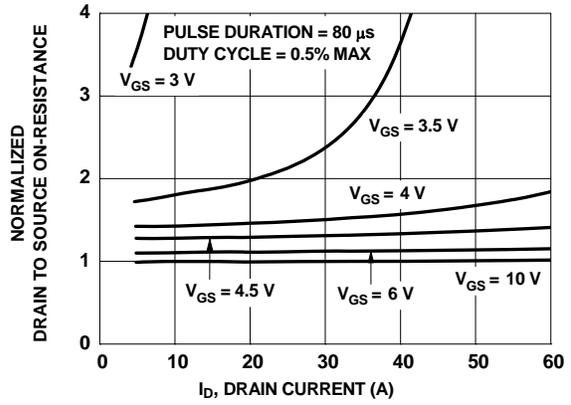


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

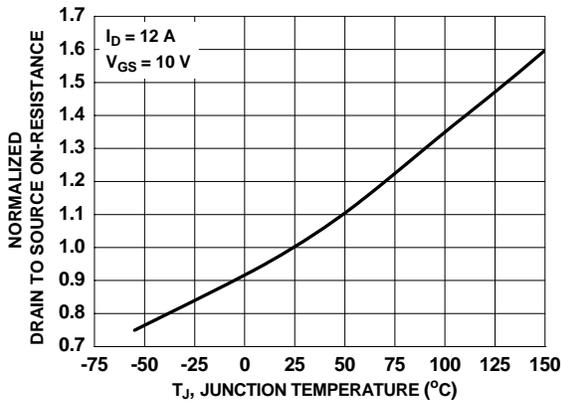


Figure 3. Normalized On Resistance vs Junction Temperature

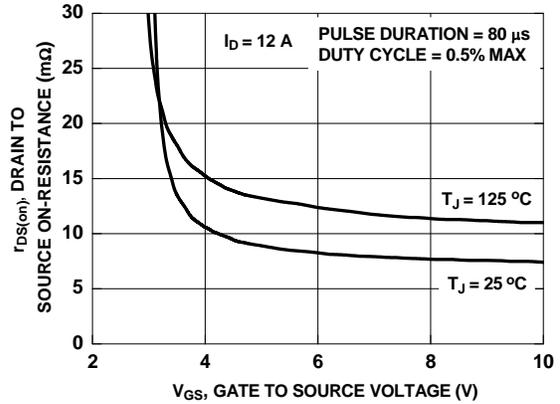
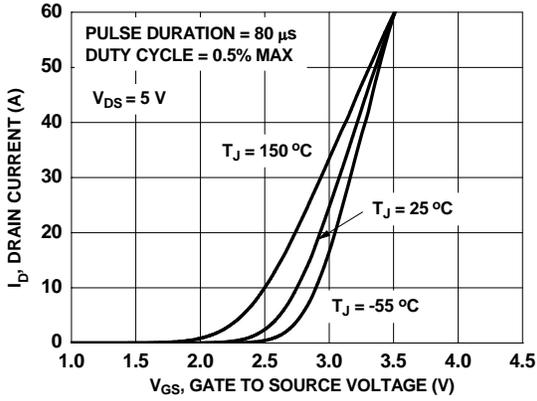
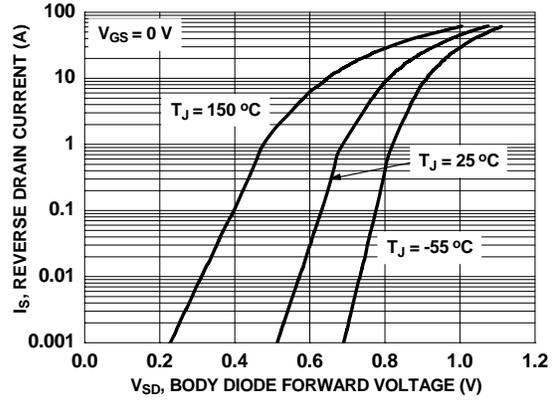


Figure 4. On-Resistance vs Gate to Source Voltage

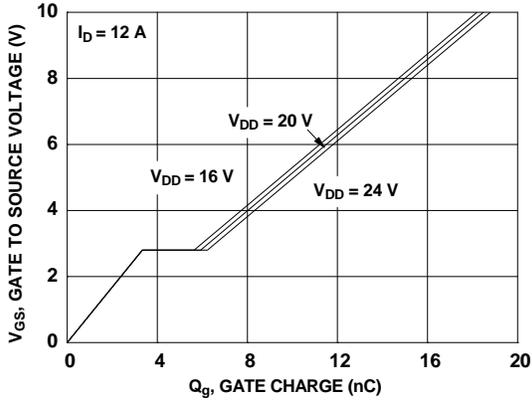
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted



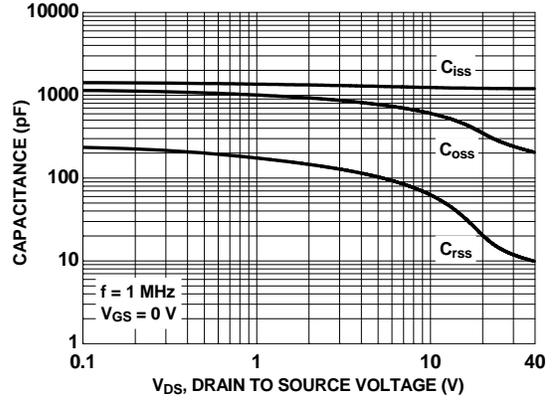
**Figure 5. Transfer Characteristics**



**Figure 6. Source to Drain Diode Forward Voltage vs Source Current**

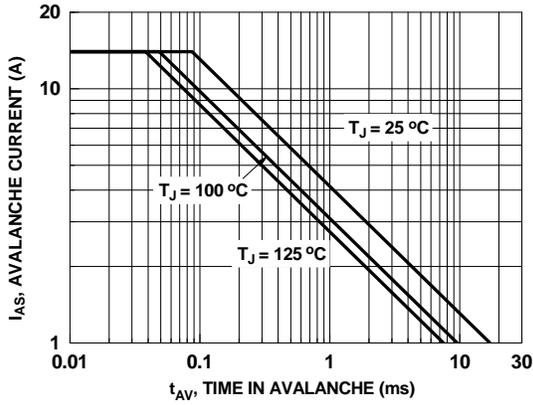


**Figure 7. Gate Charge Characteristics**

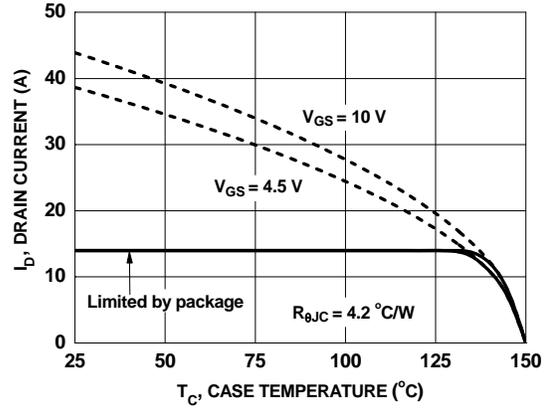


**Figure 8. Capacitance vs Drain to Source Voltage**

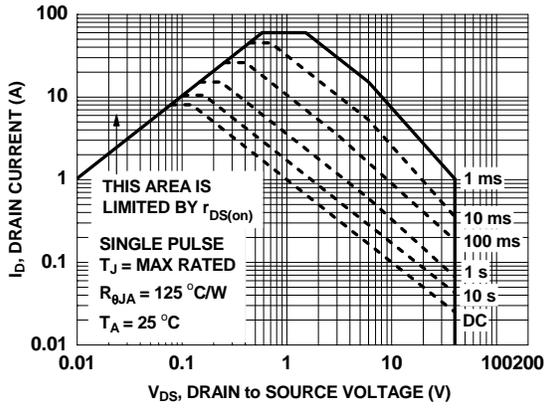
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted



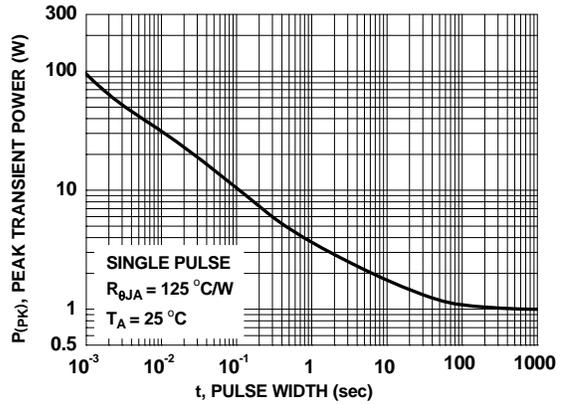
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Maximum Continuous Drain Current vs Case Temperature**

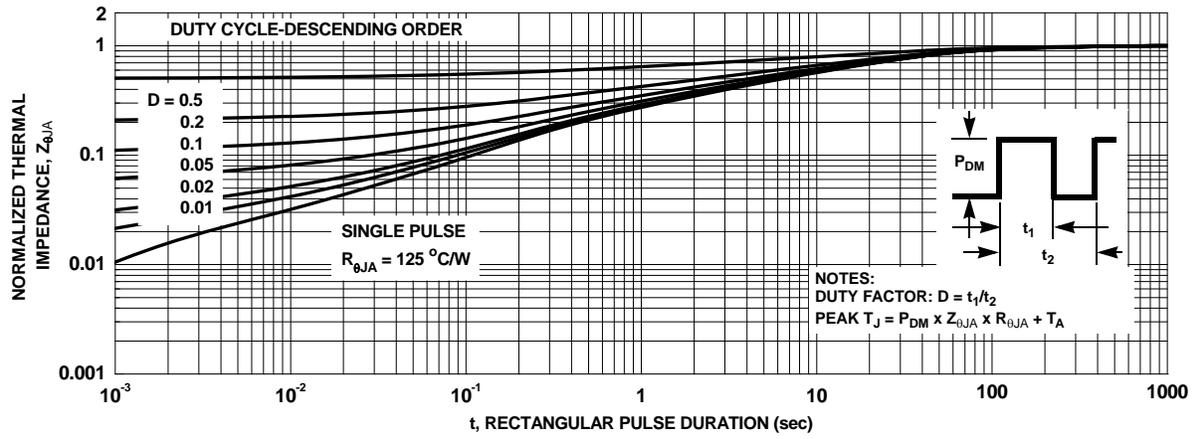


**Figure 11. Forward Bias Safe Operating Area**

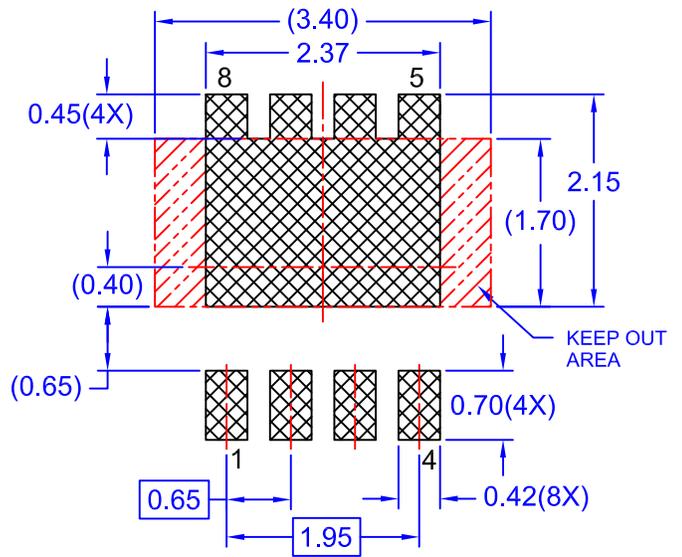
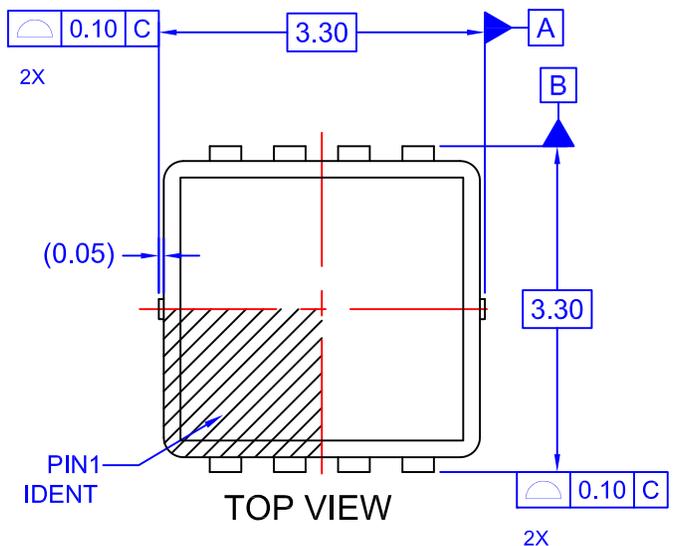


**Figure 12. Single Pulse Maximum Power Dissipation**

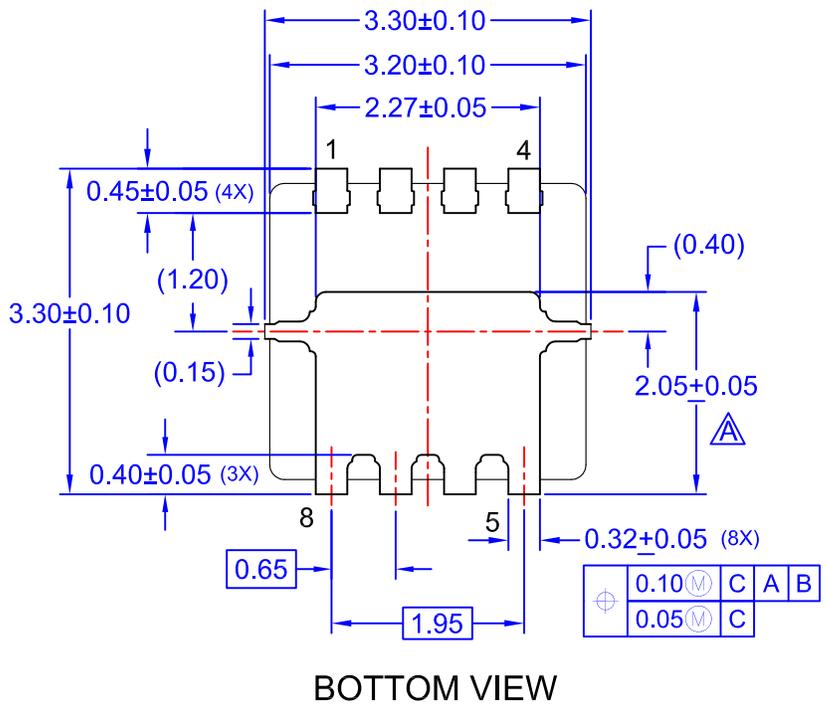
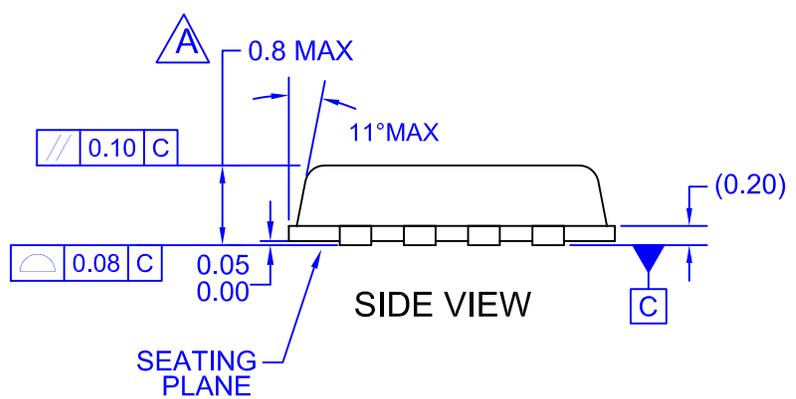
**Typical Characteristics**  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted



**Figure 13. Junction-to-Ambient Transient Thermal Response Curve**



**RECOMMENDED LAND PATTERN**



- NOTES:**
- A. EXCEPT AS NOTED, PACKAGE CONFORMS TO JEDEC REGISTRATION MO-240 VARIATION BA.
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
  - D. SEATING PLANE IS DEFINED BY TERMINAL TIPS ONLY
  - E. BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH PROTRUSIONS NOR GATE BURRS.
  - F. FLANGE DIMENSIONS INCLUDE INTERTERMINAL FLASH OR PROTRUSION. INTERTERMINAL FLASH OR PROTRUSION SHALL NOT EXCEED 0.25MM PER SIDE.
  - G. IT IS RECOMMENDED TO HAVE NO TRACES OR VIA WITHIN THE KEEP OUT AREA.
  - H. DRAWING FILENAME: MKT-MLP08Trev4.
  - I. GENERAL RADII FOR ALL CORNERS SHALL BE 0.20MM MAX.





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| FACT®                    | MTx®   | SupreMOS®                             | Xsens™           |
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| FPS™                     | OptoHiT™                                       |                                       |                  |
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